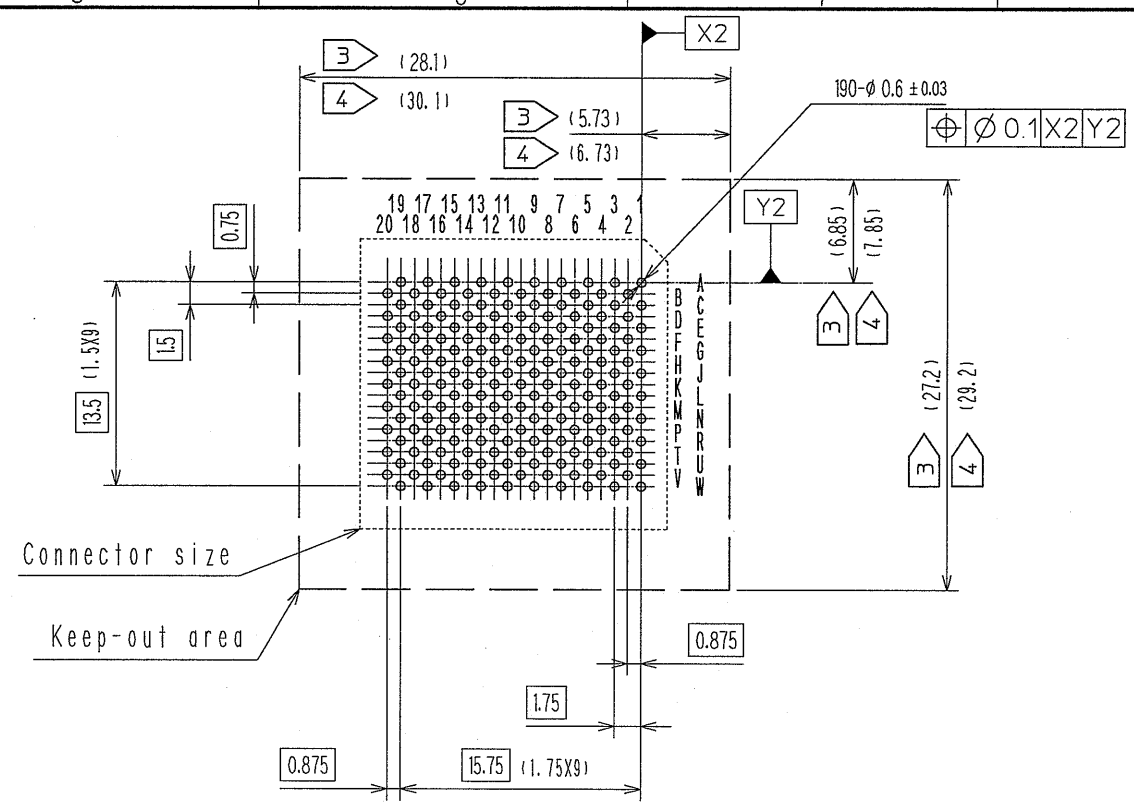
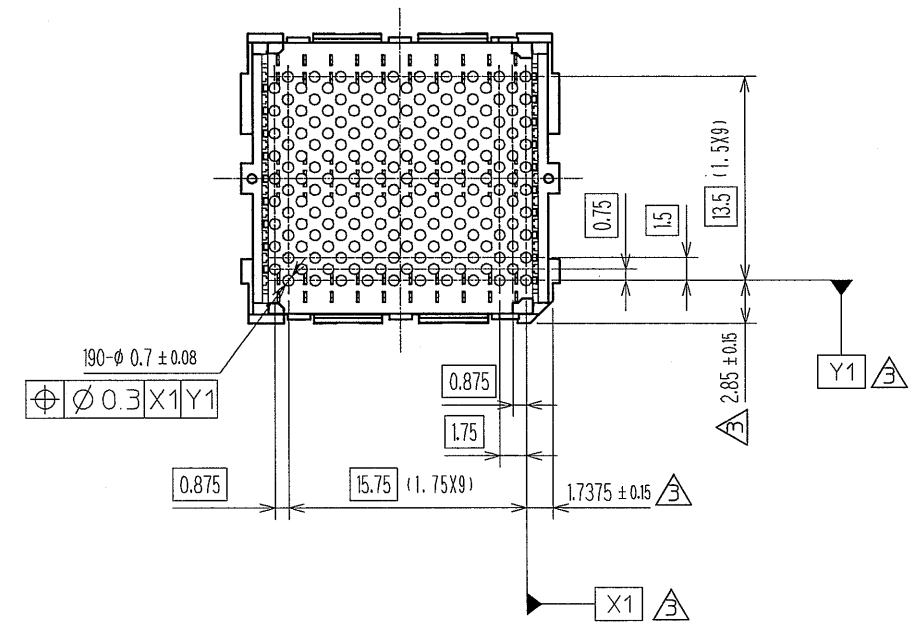
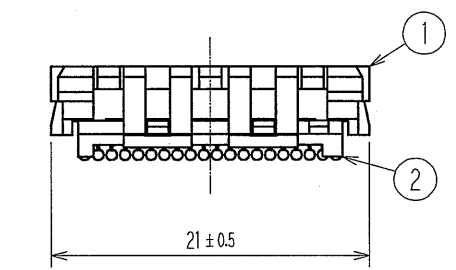
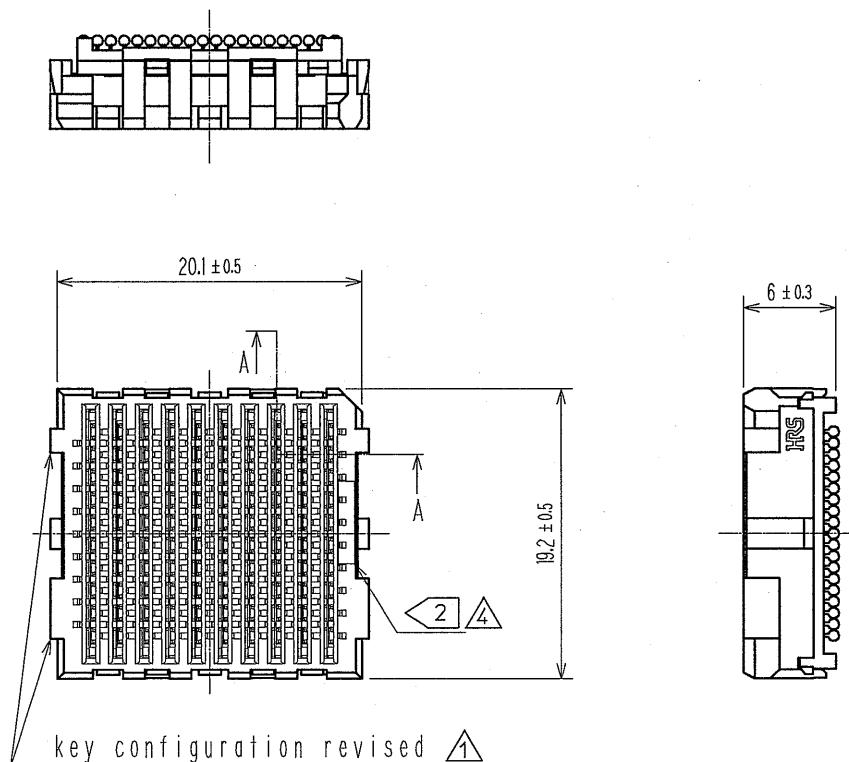
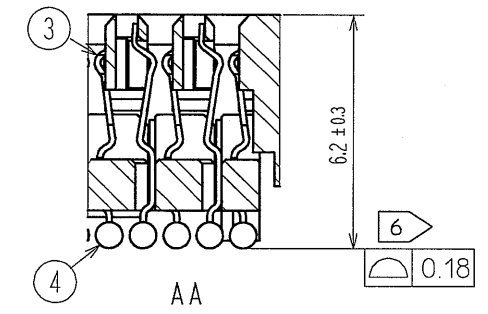




Recommended PCB Footprint
(Connector Side)



NOTE

- 1 IT3-100P-**H(**) to be mounted and locked to IT3M receptacle.
- 2 Lot no. is marked on top of the connector.
- 3 Minimum clearance for all devices.
- 4 Minimum clearance for sensitive devices.
- 5 More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".
- 6 Maximum coplanarity of the ball field is 0.18 mm.
- 7 Standard package of 120pcs are packaged in a carton box.
- 8 This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.
- 9 This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

3	Copper alloy	Contact area : Nickel(1.5μm) + Gold(0.76μm)		6	NORMEX	TAPE . WHITE
		Other area : Nickel(1.5μm)				
2	LCP	BLACK , UL94V-0		5	HIPS	TRAY . BLACK
1	LCP	BLACK , UL94V-0		4	TIN-LEAD	Sn(63)-Pb(37)
NO.	MATERIAL	FINISH. REMARKS		NO.	MATERIAL	FINISH. REMARKS

UNITS mm		SCALE 2 : 1	REV 	COUNT 3	DESCRIPTION OF REVISIONS DIS-F-004000	DESIGNED T. Saito	CHECKED M. Ezaki	DATE 15, July, 09
			APPROVED : T. Arai 09/06/2007		DRAWING NO. EDC3-157286-02			
			CHECKED : T. Matsuo 09/04/2007		PART NO. IT3M-100S-BGA(57)			
			DESIGNED : T. Takada 09/04/2007		CODE NO. CL636-0014-4-57			
			DRAWN : T. Takada 09/04/2007					

